

Datasheet revision 1.0

www.chipquik.com

Solder Wire Sn63/Pb37 No-Clean with 2.2% Flux Core 1oz Spool

Product Highlights 2.2% flux core Made from grade-A virgin metals Smaller Size

Specifications	
Alloy:	Sn63/Pb37
Wire Diameter:	0.031"
Flux Type:	No-Clean
Flux Classification:	ROL0
Melting Point:	183°C (361°F)
Packaging:	1 oz spool

Test Results

i cot neourto		
Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship	Compliant
	Coalition (EICC)	
REACH Compliance	Articles 33 and 67 of Regulation (EC)	Contains no substance >0.1% w/w that
	No 1907/2006	is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:J-STD-004B, Amendment 1 (Solder Fluxes):YesJ-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):YesRoHS 2 Directive 2011/65/EU:No